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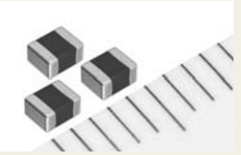

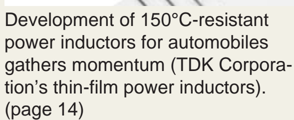

Development of 150°C-resistant power inductors for automobiles gathers momentum (TDK Corporation's thin-film power inductors). (page 14)

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